

Title (en)  
Housing for a telecommunication device

Title (de)  
Gehäuse für eine Telekommunikationsvorrichtung

Title (fr)  
Boîtier pour un dispositif de télécommunication

Publication  
**EP 2581990 A3 20141008 (DE)**

Application  
**EP 12006957 A 20121008**

Priority  
• ES 201101105 A 20111010  
• ES 201100992 U 20111010

Abstract (en)  
[origin: EP2581990A2] The housing has a chassis (1) provided with a connecting pin (2), an electronic circuit and a connecting system (4). The connecting system has a primary connecting element (41) provided with a conductive plate (411), and a secondary connecting element (42) provided with a conductive film (421). The secondary connecting element is arranged on a circuit board (32). The conductive plate is provided with a front end and a contact surface that are arranged on the conductive film such that galvanic contact is formed between conductive plate and conductive film.

IPC 8 full level  
**H01R 13/24** (2006.01); **H01R 9/24** (2006.01); **H01R 12/71** (2011.01); **H01R 13/502** (2006.01); **H01R 13/66** (2006.01); **H01R 9/05** (2006.01); **H01R 12/75** (2011.01); **H01R 13/58** (2006.01); **H01R 24/40** (2011.01)

CPC (source: EP)  
**H01R 9/2425** (2013.01); **H01R 12/714** (2013.01); **H01R 13/2464** (2013.01); **H01R 9/0515** (2013.01); **H01R 12/75** (2013.01); **H01R 13/2407** (2013.01); **H01R 13/502** (2013.01); **H01R 13/5829** (2013.01); **H01R 24/40** (2013.01)

Citation (search report)  
• [X] EP 0361821 A2 19900404 - THOMAS & BETTS CORP [US]  
• [X] US 5709557 A 19980120 - MARTIN GALEN M [US], et al  
• [X] EP 2037536 A2 20090318 - MC TECHNOLOGY GMBH [DE]  
• [A] US 5482475 A 19960109 - KAWAGUCHI AKIRA [JP]  
• [A] EP 1914842 A1 20080423 - TELEVES SA [ES]  
• [A] ES 1049159 U 20011116 - TELEVES S A Y EN SU REPRESENTA [ES]

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 2581990 A2 20130417; EP 2581990 A3 20141008; EP 2581990 B1 20181226**

DOCDB simple family (application)  
**EP 12006957 A 20121008**